

[METHOD AND SYSTEM FOR MAINTAINING UNIFORM MODULE JUNCTION TEMPERATURE DURING BURN-IN]

Abstract

A method for controlling the burn-in temperature of a semiconductor chip includes determining a DC current of the chip, and determining a difference between the DC current and a target current, the target current being selected to produce a desired chip temperature. An operating frequency of the chip is calculated, based on the determined difference between the DC current and the target current, so as generate an additional AC component of current to attain the target current.